Product End-of-Life Disassembly Instructions

Product Category: Personal Computers
Marketing Name / Model **[List multiple models if applicable.]**
HP Pavilion All-in-One MS200 PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	**Notes**	**Quantity of items included in product**
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm (Mother board, Inverter)	2
Batteries	All types including standard alkaline and lithium coin or button style batteries (Coin battery)	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries (mercury in lamps)	2
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps (LCD panel)	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

1.3 Markings for plastic parts greater than 25 grams

Plastic Part Name	**Plastic Part Description**	**Weight (grams)**	**ISO 11469:2000 Plastic Part Mark**	**Optional: Photo**
Rear Cover	Rear Cover	498	>PC+ABS (FR40) <	
Front Bezel	Front Bezel	228.1	>PC+ABS (FR40) <	
Stand Back Cover	Stand Back Cover	93	>ABS <	
Stand Base Cover	Stand Base Cover	91	>ABS <	
Stand Back Cover	Stand Back Cover	81	>ABS <	
HDD Door	HDD Door	64	>PC+ABS (FR40) <	
Hinge Door	Hinge Door	54.4	>PC+ABS (FR40) <	
Fan Housing	Fan Housing	26	>PPS<	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	**Tool Size (if applicable)**
Screw driver	1

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Release screws for Stand-ASSY, then remove Stand-ASSY.
2. Release screws for RAM-door and HDD-door, then remove those doors.
3. Release screw for ODD-module, then use screw driver to push ODD-module out of system.
4. Remove Rear-Cover-ASSY.
5. Release screws for inventer, and then remove inventer(Figure 1)

6. Release screws for M/B shielding, then remove M/B shielding. (Figure 2)
7. Release RTC battery form motherboard(Figure 2)
8. Release screws for Thermal, Fan, all PCBAs and Speaker, then remove all of them.
9. Release screws form Panel-ASSY to Bezel, then remove Panel-ASSY.(Figure 3)
10. Release screws for Panel-ASSY, then remove middle-frame.
11. Please refer below figure 4 for detailed disassembly steps.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1 Inverter

Figure 2 Motherboard

Figure 3

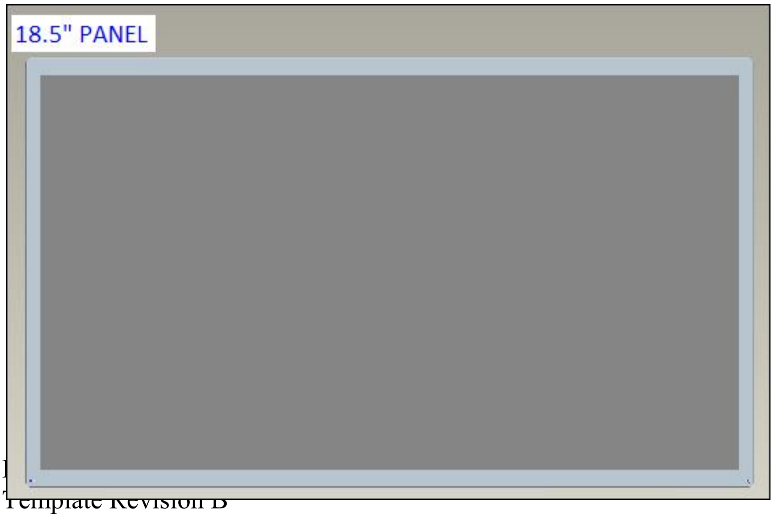

Figure 4 Disassembly instructions for LCD panel